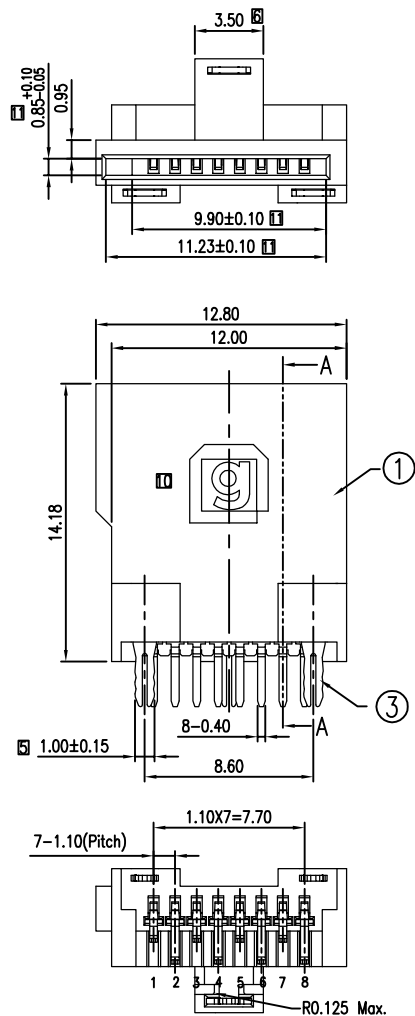
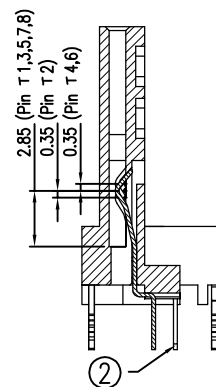
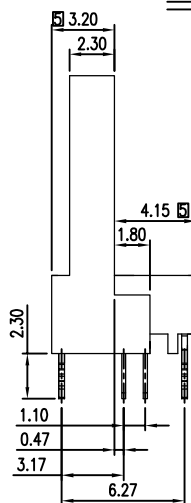
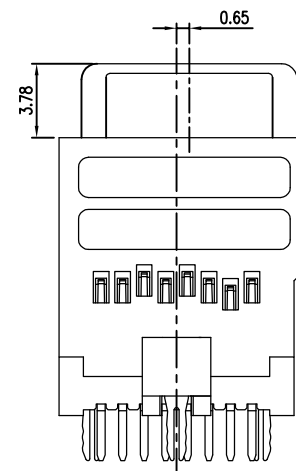


Recommended PCB layout

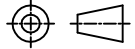


SECTION A-A



PinT	Description
1	DAT2
2	CD/DAT3
3	CMD
4	V _{DD}
5	CLK
6	V _{SS}
7	DAT0
8	DAT1

13	ADD PACKAGE OPTION	Terry	07/16/19'
12	CHANGE NOTES 3a, WAS -25°C	AXL	10/3/16'
11	MODIFY TOLERANCE	Terry	07/21/10'
10	ADD LOGO	Terry	07/07/10'
9	ADD FILLET	Terry	05/27/10'
8	ADD CHAMFER	Terry	05/25/10'
7	MODIFY DRAWING	Terry	05/14/10'
6	CONTACT PLATING	Terry	05/04/10'
5	MODIFY BOARD LOCK	Terry	04/29/10'
4	MODIFY BOARD LOCK	Terry	04/27/10'
3	MODIFY DRAWING	Terry	04/22/10'
REV.	ECN NO.		

TOLERANCE		 A Genesis Electro-Mechanical Company		TITLE: MICRO SD CARD VERTICAL DIP TYPE	
LINEAR	ANGLES				
X.±0.50	X°.±3°	APPD:		PART NO. MSDV-2008-AK*0*01	
.X±0.40	.X°.±3°	MAT'L:		DWG NO. GTi10-25051	
.XX±0.30	.XX°.±3°	CHKD: Terry	FINISH:		UNITS mm
.XXX°.±3°	.XXX°.±3°	DRWN: Terry	Q'TY:		
				SCALE	SHEET
				NONE	10F2
				REV	13

- 2 Notes:
- Electrical:
 - Voltage Rating: 50VAC (r.m.s)
 - Current Rating: 0.5Amperes.
 - Insulation Resistance: 1000M ohms min. initial.
 - Dielectric Withstand Voltage: AC 500V/1 minute.
 - Contact Resistance: 100 m ohms max. initial;
 - Mechanical:
 - Material:
Contacts: Phosphor Bronze, T=0.2mm.
☒ Board Lock: Brass, T=0.3mm.
Housing Flammability Rating: PBT, Black, UL94V-0
 - Plating:
Contacts: Gold plated ☒ 12u", Solder tail Tin plated 80u", 50u" nickel underplated overall.
Board Lock: Tin plated 80u", 50u" nickel underplated overall.
 - Durability: 10,000 Cycles.
 - Mating force: 25N Max.
☒ Unmating force: 1.5N Min.
 - Solderability: More than 90% of solderable area
 - Soldering Profile: 260° for 10 seconds without remarkable deterioration.
 - Environmental:
☒ a. Operating Temperature: -40°C to +85°C.
Storage Temperature: -40°C to +85°C.
b. Steady State Humidity: 90%~95% humidity on 40±2°C for 96hours.
c. Thermal Shock: 5 cycles of -55°C to 85°C.
d. Vibration Resistance: With dummy card applying DC 100mA,
Frequency: 10-2000Hz
Acceleration: 20m/s²
Sweep rate: 10-2000-10Hz in 5min.
Duration: 50min.(10 cyc)
Specimen to be excited along X,Y,and Z axes.(total:150min)
e. Impact Resistance: With dummy card applying DC 100mA,
Shock Waveform: Half sinewave
Acceleration: 490m/s²
Impact duration: 11msec.
9 total impacts delivered 3 each along X,Y, and Z axes. (total:9 impacts)
f. After test, contact resistance increase 40m ohms Max.
 - Compliance:
 - RoHS Compliance.

☒ PART. NUMBER

☒ MSDV-20 08 - A K * 0 * 01
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- CONNECTOR:
MSDV: MICRO SD CARD.
- TYPE
20: MICRO SD CRAD VERTICAL DIP TYPE
- POSITIONS
08: 08 POSITION
- INSULATOR MATERIAL
A: PBT
- INSULATOR COLOR
K: BLACK
- CONTACT PLATING
A: GOLD PLATING 12u'
- SHIELD PLATING
0: NONE SHIELD
- SHIELD PLATING
T: TRAY
R: TAPE REEL

PART NO.	MSDV-2008-AK*0*01	SHEET	REVISION
DWG NO.	GTi10-25051	2 OF 2	SEE SHEET 1

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES\(宏致\)](#)